

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IAUA250N04S6N007	**Issued**	08. April 2022
MA#	MA005351830		
Package	PG-HSOF-5-1	**Weight***	369.19 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.904	0.52	0.52	5157	5157
leadframe	inorganic material	phosphorus	7723-14-0	0.015			39	
	non noble metal	iron	7439-89-6	0.048	0.01		131	
	non noble metal	copper	7440-50-8	48.418	13.11	13.12	131147	131317
wire	noble metal	gold	7440-57-5	0.037	0.01	0.01	101	101
encapsulation	inorganic material	zincoxide	1314-13-2	1.415	0.38		3833	
	miscellaneous	miscellaneous	-	5.661	1.53		15332	
	plastics	epoxy resin	-	21.227	5.75		57496	
	inorganic material	silicondioxide	60676-86-0	113.210	30.66	38.32	306648	383309
leadfinish	non noble metal	tin	7440-31-5	3.673	0.99	0.99	9949	9949
plating	noble metal	silver	7440-22-4	0.015			41	41
solder	non noble metal	tin	7440-31-5	0.050	0.01		134	
	noble metal	silver	7440-22-4	0.062	0.02		168	
	non noble metal	lead	7439-92-1	2.368	0.64	0.67	6414	6716
heat sink clip	inorganic material	phosphorus	7723-14-0	0.008			23	
	non noble metal	iron	7439-89-6	0.028	0.01		77	
	non noble metal	copper	7440-50-8	28.224	7.64	7.65	76449	76549
heatspreader	inorganic material	phosphorus	7723-14-0	0.043	0.01		116	
	non noble metal	iron	7439-89-6	0.143	0.04		387	
	non noble metal	copper	7440-50-8	142.638	38.67	38.72	386358	386861
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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